



Parameter	Rating	Units
Blocking Voltage	350	V _p
Load Current	120	mA _{rms} / mA _{DC}
On-Resistance (max)	50	Ω

Features

- 1500V_{rms} Input/Output Isolation
- Low Drive Power Requirements (TTL/CMOS Compatible)
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 4-Pin SOP Package
- Machine Insertable, Wave Solderable
- Tape & Reel Version Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The CPC1150N is a miniature single-pole, normally closed (1-Form-B) solid state relay that uses optically coupled MOSFET technology to provide 1500V_{rms} of input to output isolation.

Its optically coupled output, which uses the patented OptoMOS architecture, is controlled by a highly efficient GaAIAs infrared LED.

State of the art double-molded vertical construction packaging enables the CPC1150N to be one of the world's smallest 4-pin solid state relays. It offers board space savings over the competitor's larger 4-pin SOP relay.

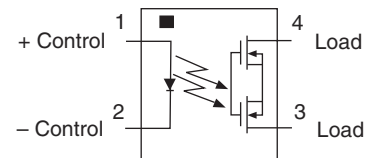
Approvals

- UL 1577 Approved Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN 60950 Certified Component:
TUV Certificate B 10 05 49410 006

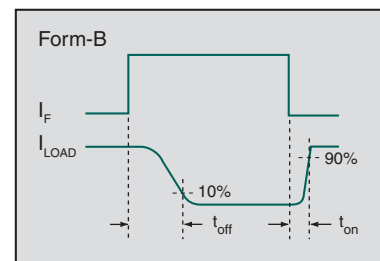
Ordering Information

Part #	Description
CPC1150N	4-Pin SOP (100/tube)
CPC1150NTR	4-Pin SOP (2000/reel)

Pin Configuration



Switching Characteristics of Normally Closed Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	350	V _P
Reverse Input Voltage	5	V
Input Control Current Peak (10ms)	50	mA
	1	A
Input Power Dissipation	70	mW
Total Power Dissipation ¹	400	mW
Isolation Voltage, Input to Output	1500	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

¹ Derate linearly 3.33 mW / °C

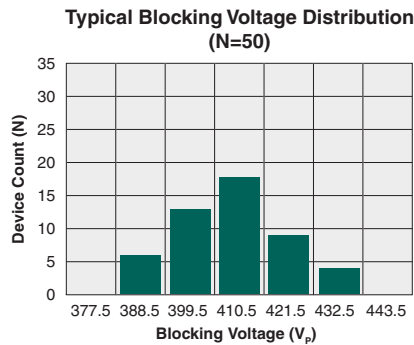
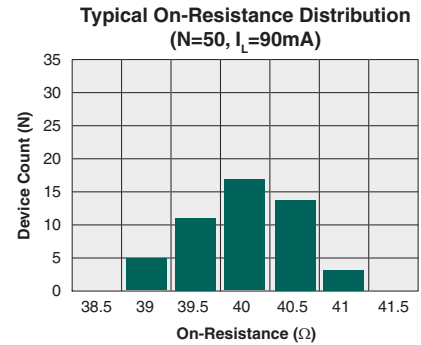
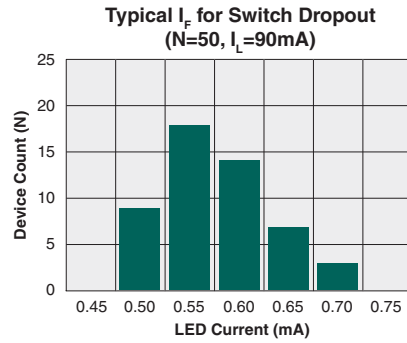
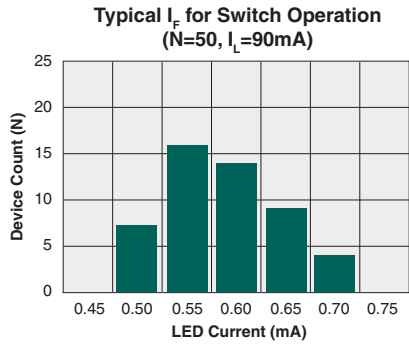
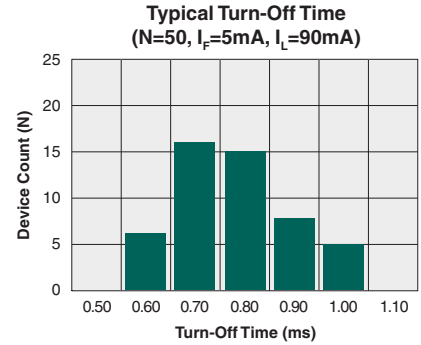
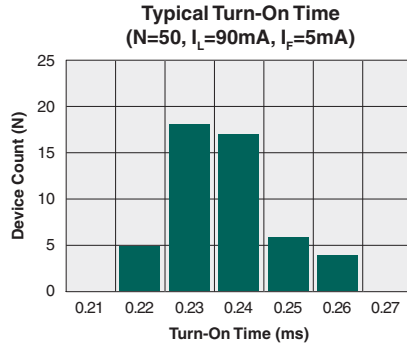
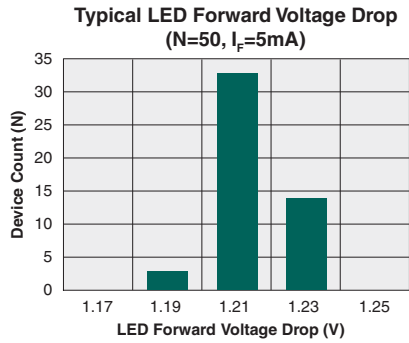
Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current Continuous ¹	-	I _L	-	-	120	mA _{rms} / mA _{DC}
	t = 10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance	I _L = 120mA	R _{ON}	-	-	50	Ω
Off-State Leakage Current	I _F = 2mA, V _L = 350V _P	I _{LEAK}	-	-	5	μA
Switching Speeds	I _F = 5mA, V _L = 10V	t _{on}	-	-	1	ms
		t _{off}	-	-	2	
Output Capacitance	I _F = 2mA, V _L = 50V, f = 1MHz	C _{OUT}	-	25	-	pF
Input Characteristics						
Input Control Current to Activate ²	I _L = 120mA	I _F	-	0.6	2	mA
Input Control Current to Deactivate	-	I _F	0.3	0.55	-	mA
Input Voltage Drop	I _F = 5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R = 5V	I _R	-	-	10	μA
Common Characteristics						
Capacitance, Input to Output	-	C _{I/O}	-	1	-	pF

¹ Load current derates linearly from 120mA @ 25°C to 85mA @ 85°C.

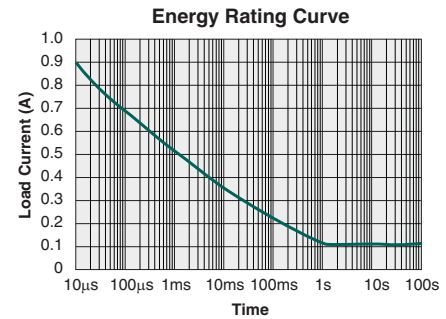
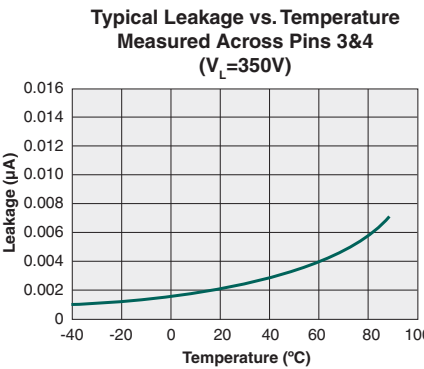
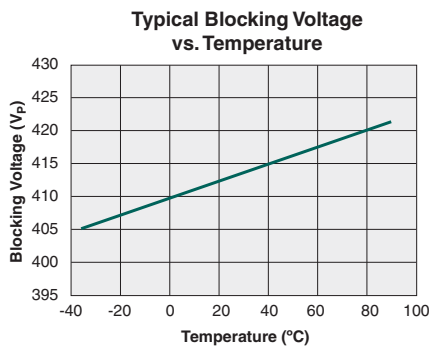
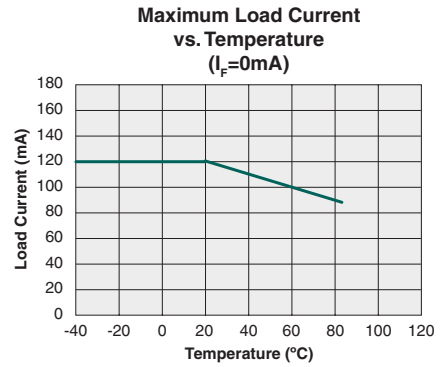
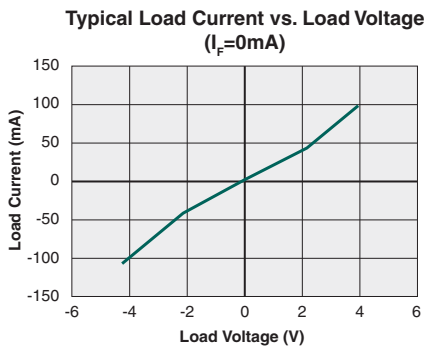
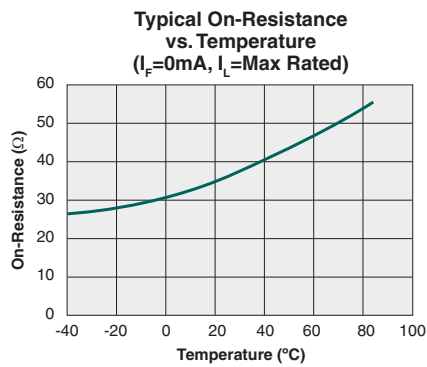
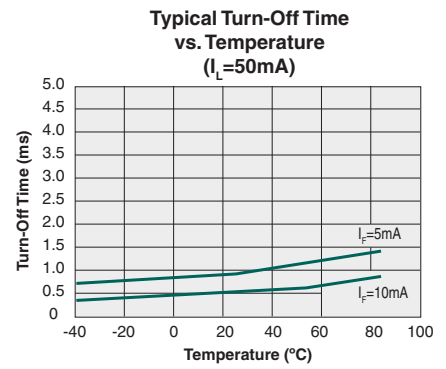
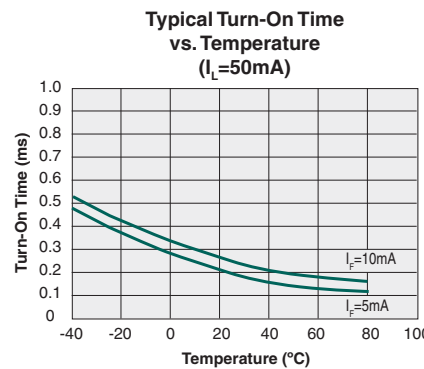
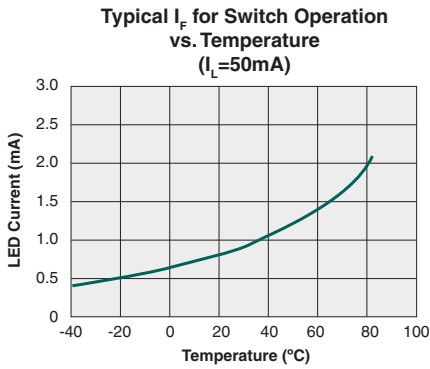
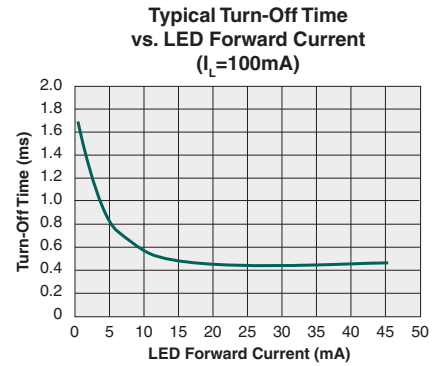
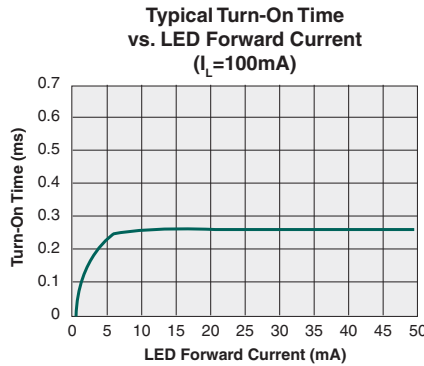
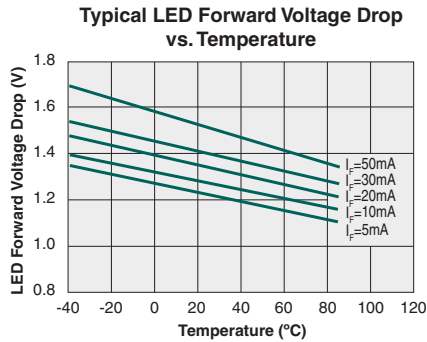
² For applications requiring high temperature operation (greater than 60°C) a LED drive current of 4mA is recommended.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

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Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1150N	MSL 3

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
CPC1150N	260°C for 30 seconds

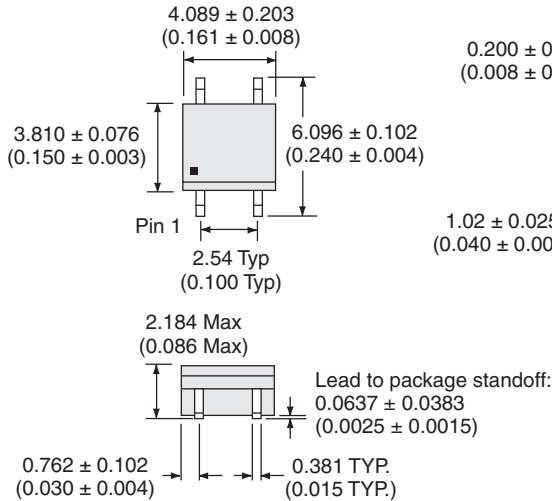
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

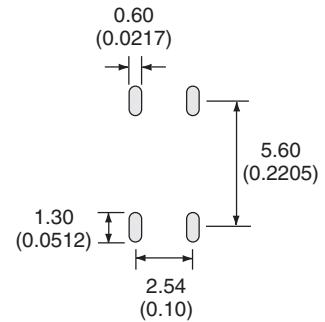


Mechanical Dimensions

CPC1150N

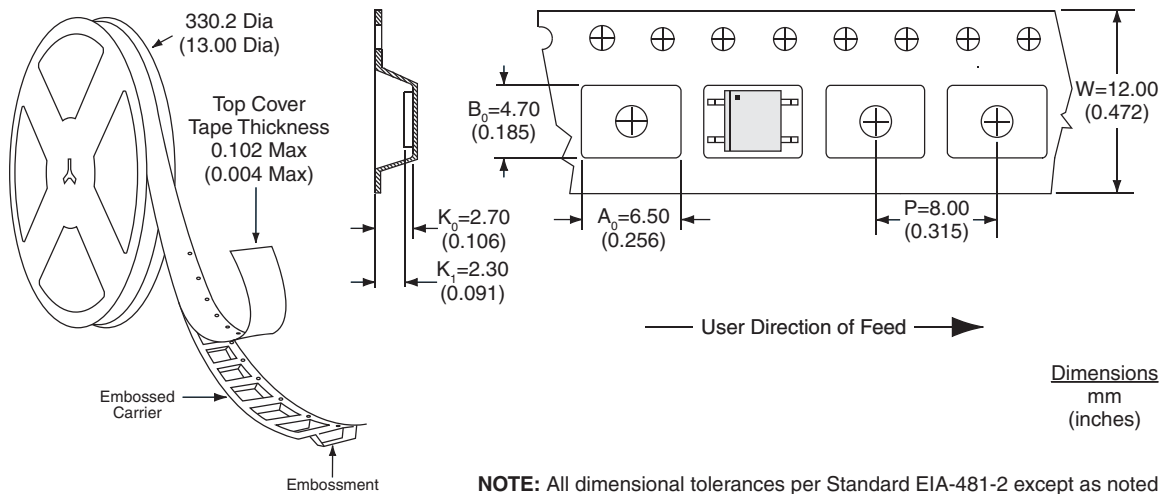


Recommended PCB Land Pattern



Dimensions
mm
(inches)

CPC1150NTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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Specification: DS-CPC1150N-R09
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